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Nov 30, 1989

DERWENT-ACC-NO: 1990-018353

DERWENT-WEEK: 199003

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TITLE: Pattern formation by double-layer-resist method - comprises forming polymer resist on flattening layer of organic material on substrate, patterning resist by radiation and dry-etching

PATENT-ASSIGNEE:

ASSIGNEE

CODE

FUJITSU LTD

FUIT

PRIORITY-DATA: 1988JP-0129072 (May 26, 1988)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<u>JP 01297644 A</u>	November 30, 1989		005	

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP 01297644A	May 26, 1988	1988JP-0129072	

INT-CL (IPC): G03C 1/71; H01L 21/30

ABSTRACTED-PUB-NO: JP 01297644A

BASIC-ABSTRACT:

Resist material, comprises polymer of general formula (I) or its copolymer.

Pattern formation by double-layer-resist method comprises the steps of: providing a flattening layer consisting of organic material on substrate; providing resist comprising polymer of general formula (I) or its copolymer on the top of the flattening layer; patterning the resist by radiation; and dry-etching the flattening layer using thus formed pattern as mask.

USE/ADVANTAGE - The resist material and the pattern formation are useful for prepn. of semiconductor integrated circuit. The material acts as radiation-sensitive negative-type resist, and has high sensitivity, superior resolution and large selectivity ratio with the underlayer.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: PATTERN FORMATION DOUBLE LAYER RESIST METHOD COMPRISE FORMING POLYMER RESIST FLATTEN LAYER ORGANIC MATERIAL SUBSTRATE PATTERN RESIST RADIATE DRY ETCH

DERWENT-CLASS: A89 G06 L03 P83 U11

CPI-CODES: A04-C; A12-E07C; A12-L02B2; G06-C14; G06-D06; G06-F03C; L04-C05; L04-C06B;

EPI-CODES: U11-A06;

POLYMER-MULTIPUNCH-CODES-AND-KEY-SERIALS:

Key Serials: 0202 0231 0353 0354 2016 2020 2194 2198 2419 2493 2718 3279 2805

Multipunch Codes: 014 034 04- 05- 055 059 229 231 353 359 431 473 477 524 58& 623
627 658 688

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1990-007932

Non-CPI Secondary Accession Numbers: N1990-013993